



FIG. I(A)

FORMATION OF INSULATING LAYER 101a

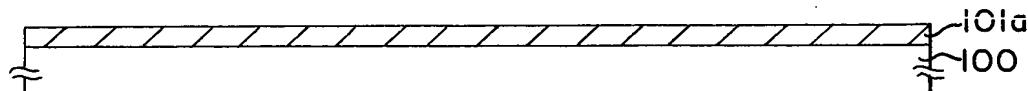


FIG. I(B)

SEQUENTIAL FORMATION OF INSULATING LAYER 101b
AND SEMICONDUCTOR FILM

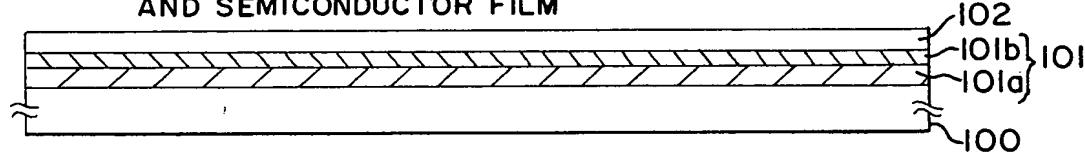


FIG. I(C)

CRYSTALLIZATION

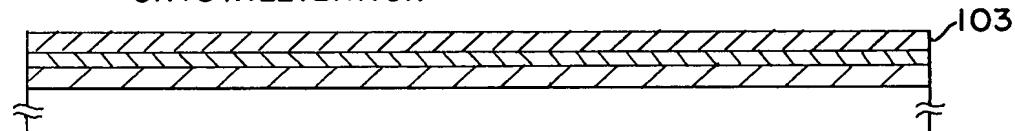


FIG. I(D)

FORMATION OF ACTIVE LAYER AND GATE INSULATING
FILM

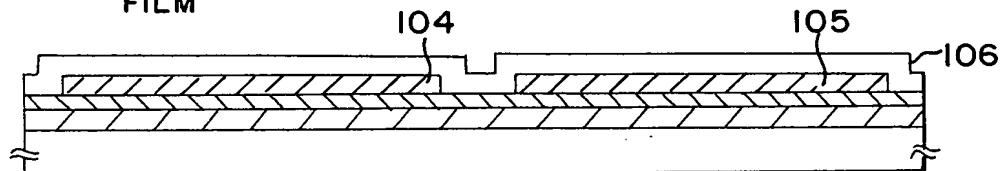


FIG. I(E)

FORMATION OF GATE WIRING

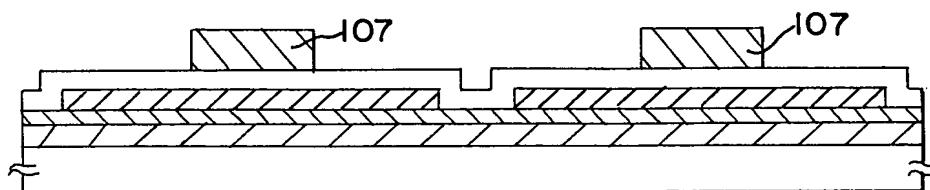




FIG.2(A)

ANODIC OXIDATION

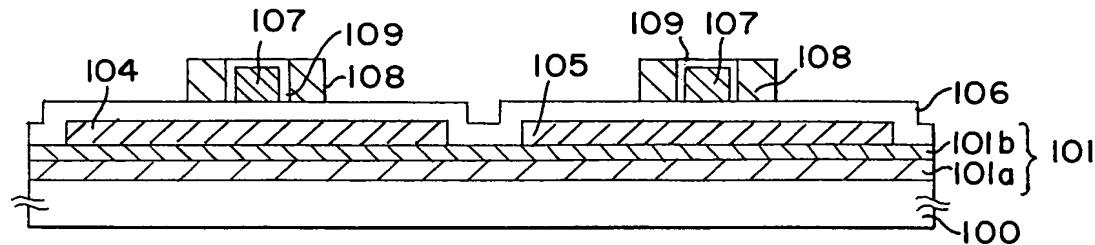


FIG.2(B)

DOPING WITH PHOSPHORUS

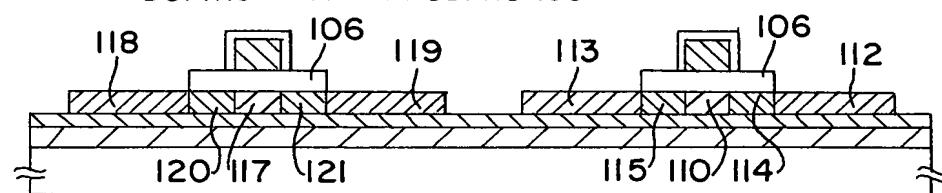


FIG.2(C)

DOPING WITH BORON

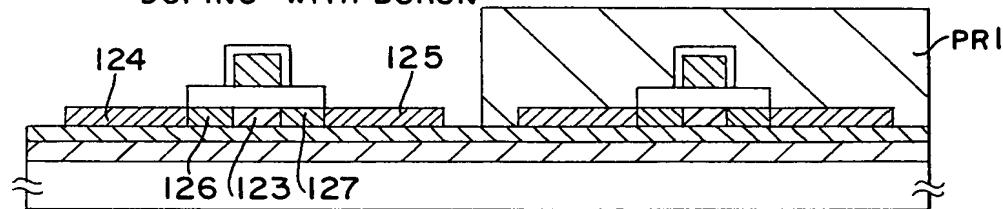
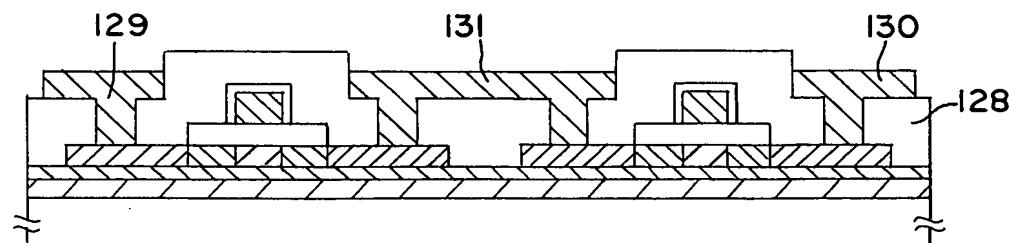


FIG.2(D)

FORMATION OF WIRING



P-CHANNEL TYPE

N-CHANNEL TYPE



FIG. 3

		SUBSTRATE 1	SUBSTRATE 2	SUBSTRATE 3	SUBSTRATE 4
FLOW RATE OF RAW MATERIAL GAS	Si H 4	4		10	15
	N 2 O	400		20	20
HEAT TREATMENT	N H 3	0		100	200
	CONDUCTED	NO	NO	NO	NO
COMPOSITION RATIO (ATOMIC %)	N	7. 0	24. 0	44. 1	
	O	59. 5	26. 5	6. 0	
Si		32. 0	33. 0	34. 4	
	H	1. 5	16. 5	15. 5	
REFRACTIVE INDEX		1. 4566	1. 7468	1. 7975	

FILM FORMING CONDITIONS AND PHYSICAL PROPERTIES
OF INSULATING LAYER (SILICON OXIDE NITRIDE LAYER) 101a



FIG. 4(A)

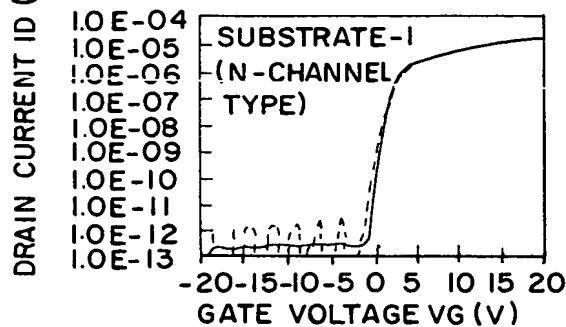


FIG. 4 (B)

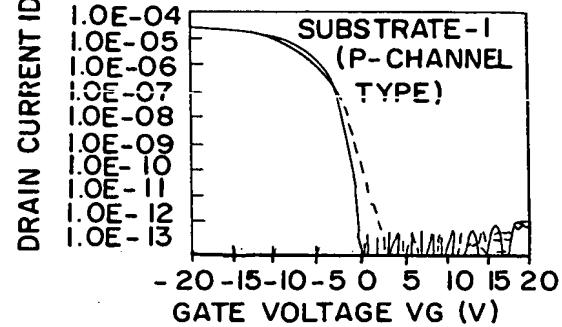


FIG. 4 (C)

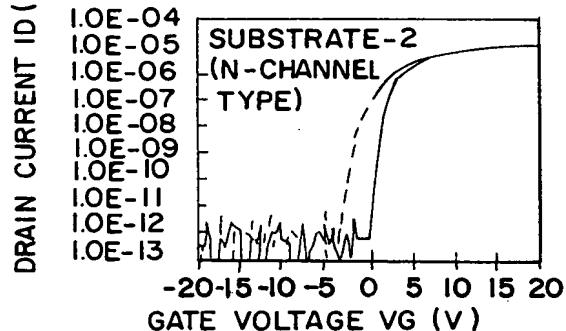


FIG. 4 (D)

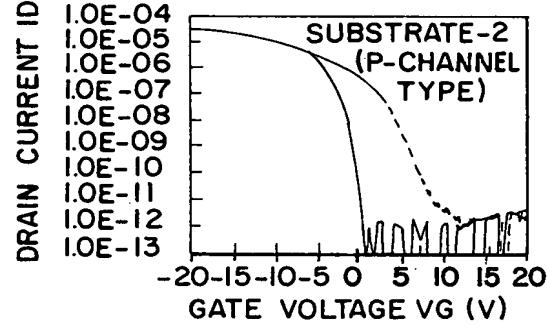


FIG. 4 (E)

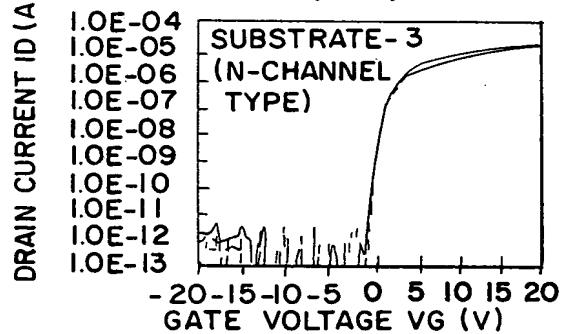


FIG. 4 (F)

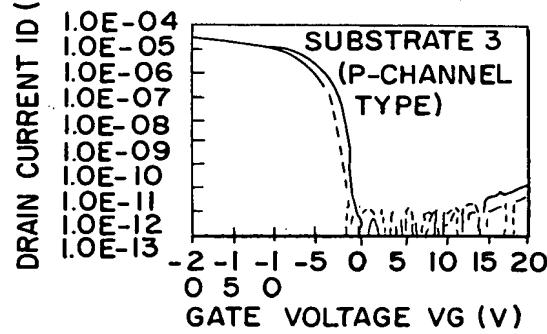


FIG. 4 (G)

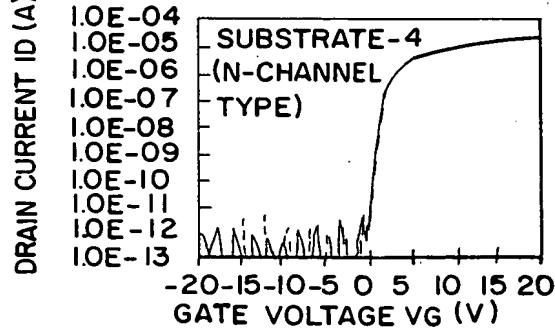


FIG. 4 (H)

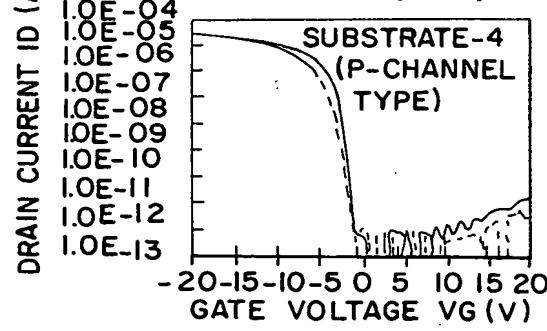




FIG. 5A

N-CHANNEL TYPE ($L/W = 5.6/7.5 \mu m$)
 P-CHANNEL TYPE ($L/W = 5.6/7.5 \mu m$)

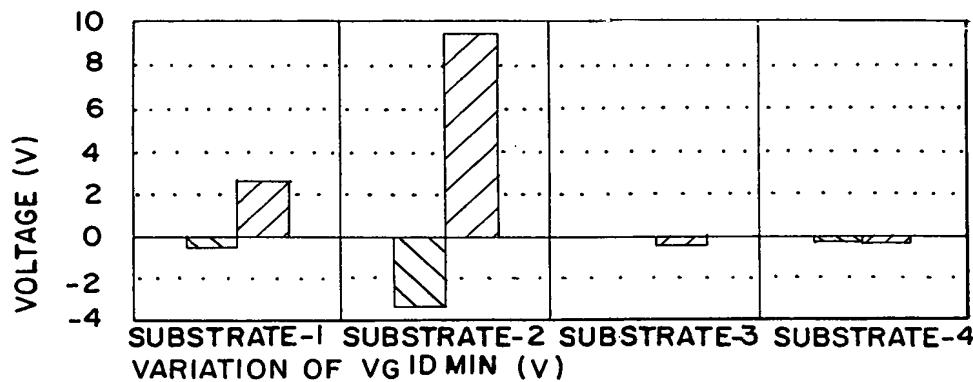


FIG. 5B

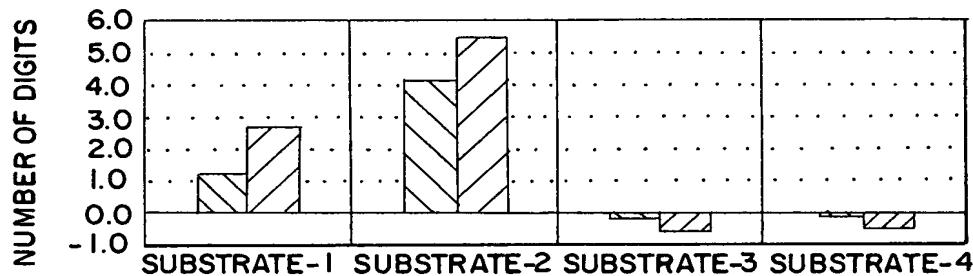


FIG. 5C

CHANGE OF NUMBER OF DIGITS OF I CUT

* STRESS CONDITIONS

150°C, 1 HOUR, VG: 20V(N-CHANNEL TYPE), -20V(P-CHANNEL TYPE),
 $VD = VS = 0V$

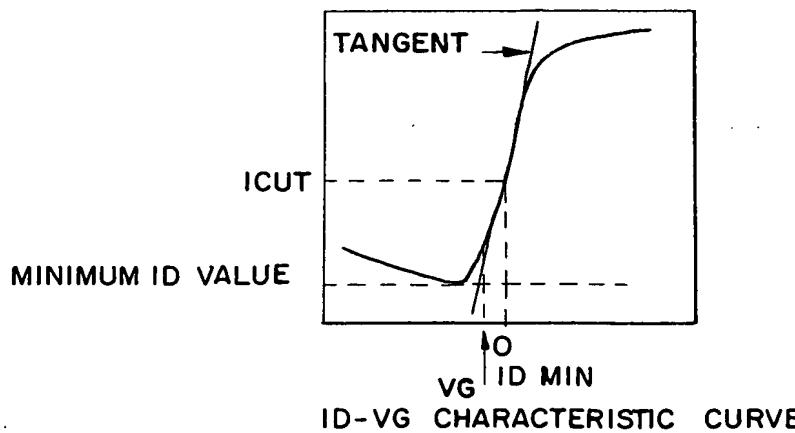




FIG. 6

DRIVER CIRCUIT (CMOS CIRCUIT)

PIXEL MATRIX CIRCUIT

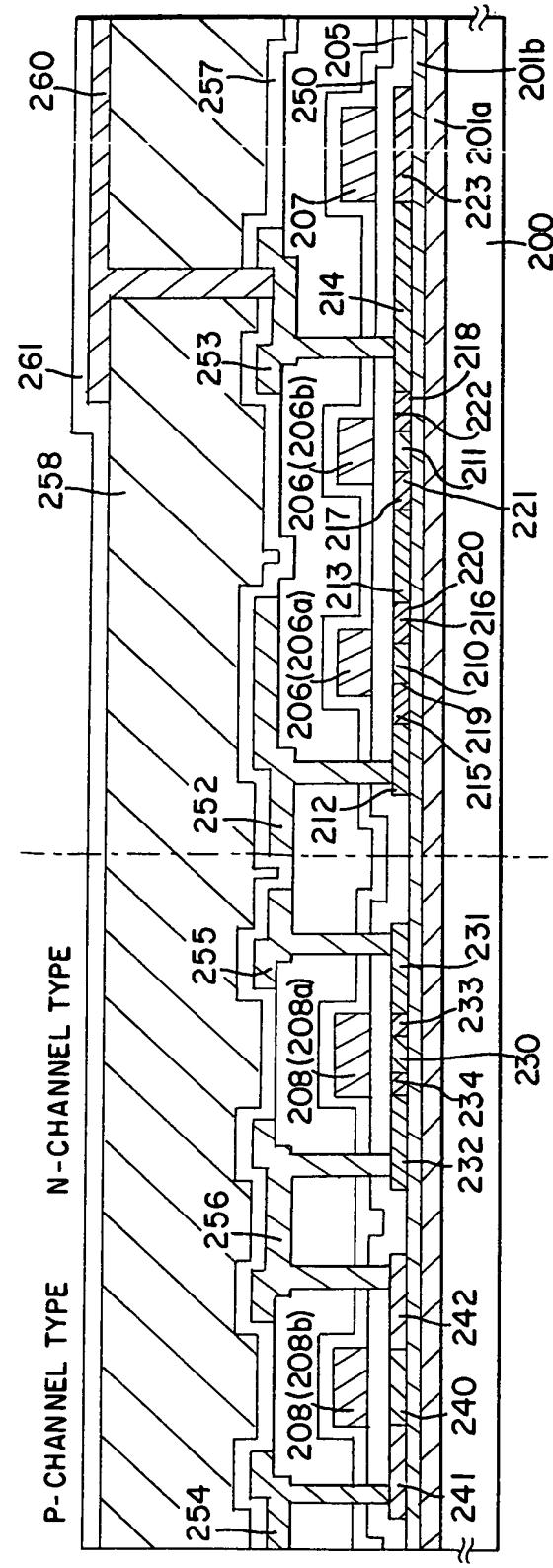




FIG. 7 (A)

FORMATION OF UNDERLYING FILM, ACTIVE LAYER AND GATE INSULATING FILM

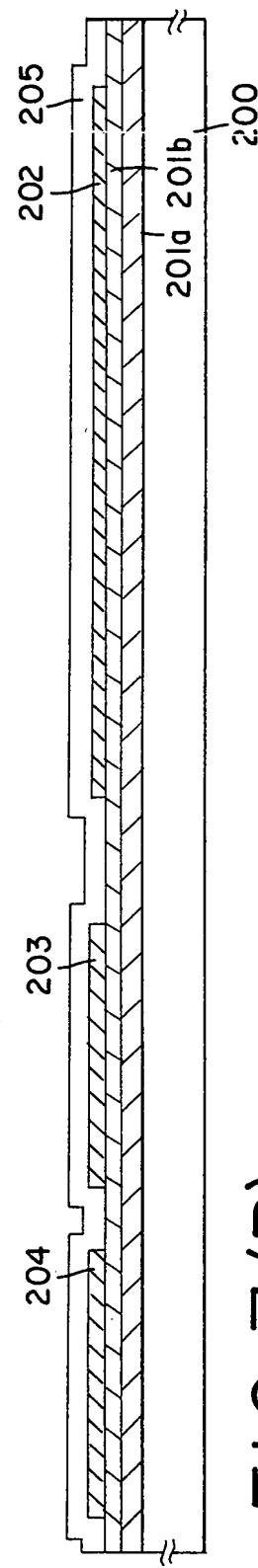


FIG. 7 (B)

DOPING PROCESS OF PHOSPHORUS (FORMATION OF n-TYPE REGION)

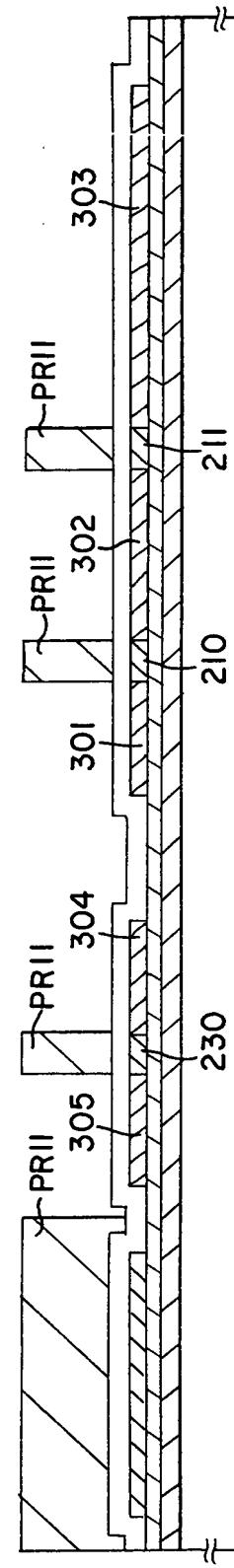
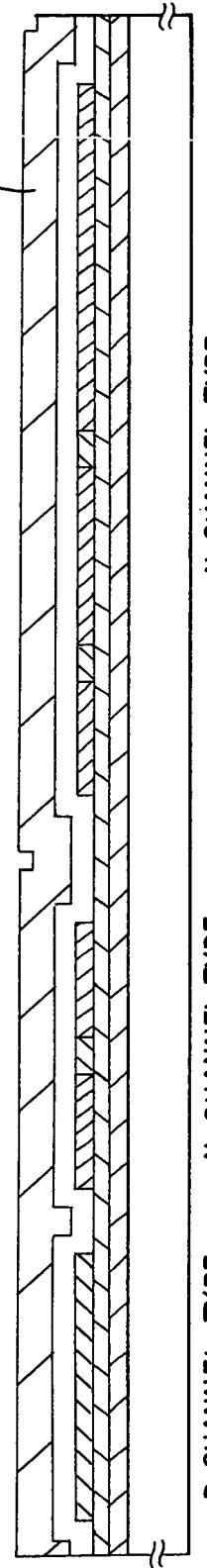


FIG. 7 (C)

FORMATION OF CONDUCTIVE FILM



P-CHANNEL TYPE N-CHANNEL TYPE N-CHANNEL TYPE



FIG. 8(A)

DOPING WITH BORON (FORMATION OF P+ - TYPE REGION)

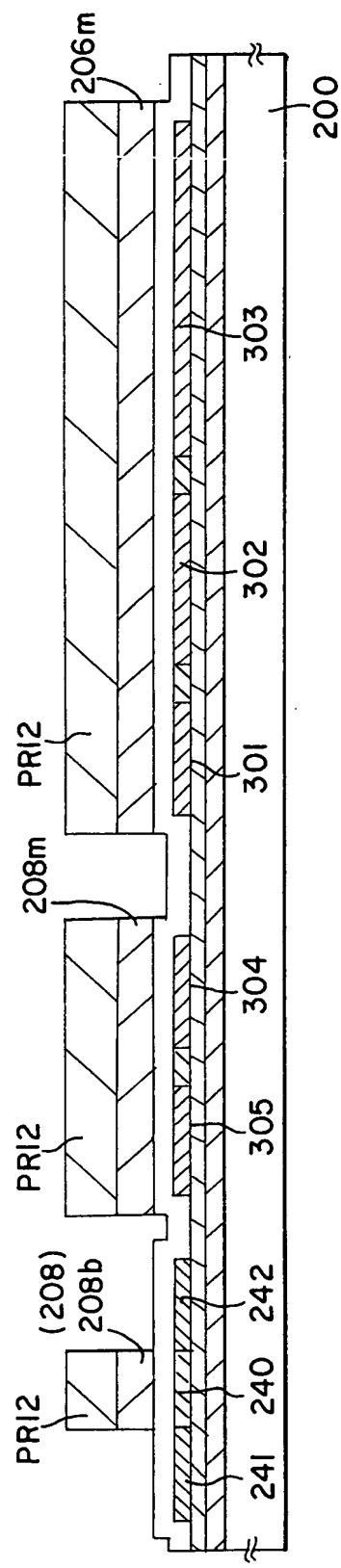
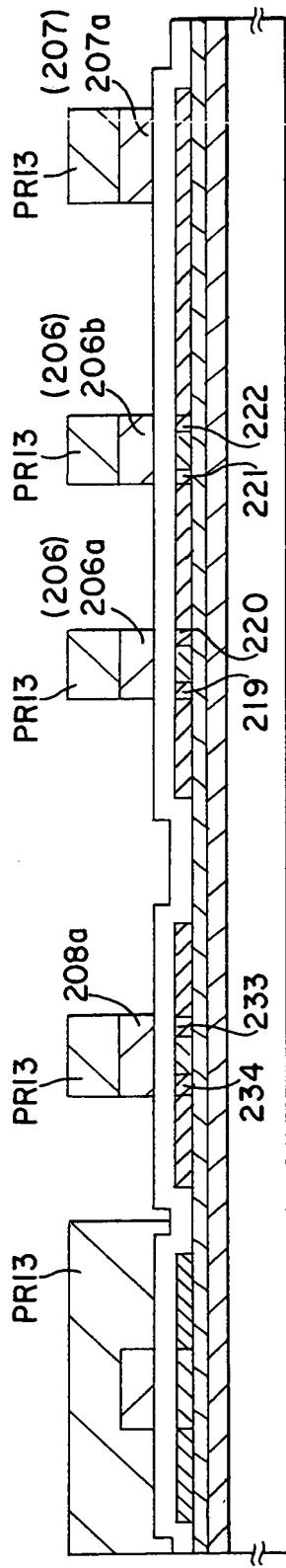


FIG. 8(B)

FORMATION OF WIRING



P-CHANNEL TYPE N-CHANNEL TYPE N - CHANNEL TYPE



FIG. 9(A)

DOPING WITH PHOSPHORUS (FORMATION OF n+- TYPE REGION)

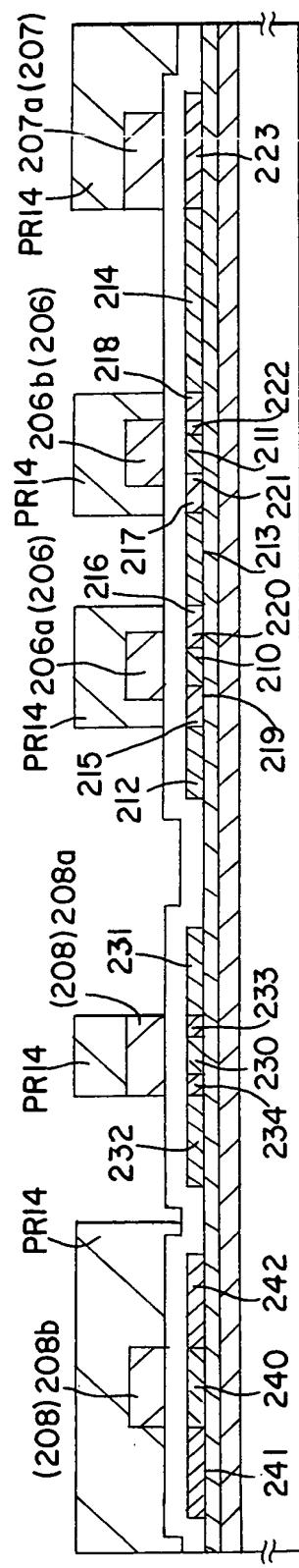
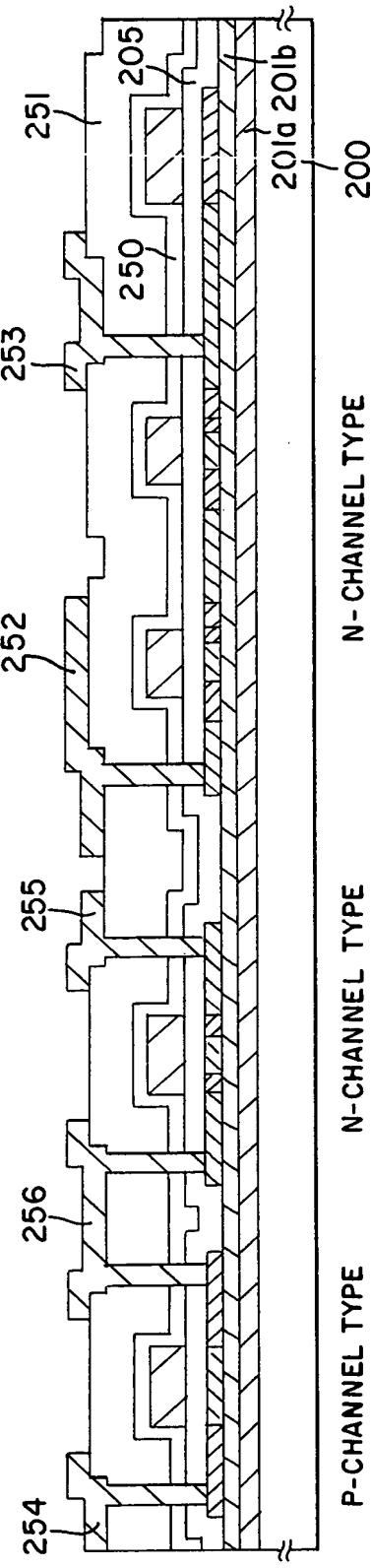


FIG. 9(B)

FORMATION OF WIRING AND ELECTRODE



P-CHANNEL TYPE N-CHANNEL TYPE N-CHANNEL TYPE

200 201a 201b



FIG. 10

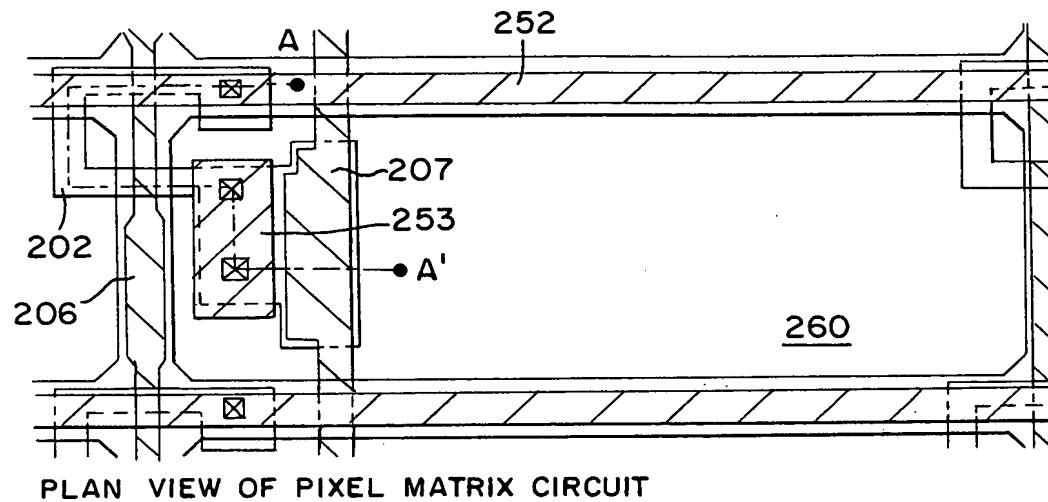


FIG. 11

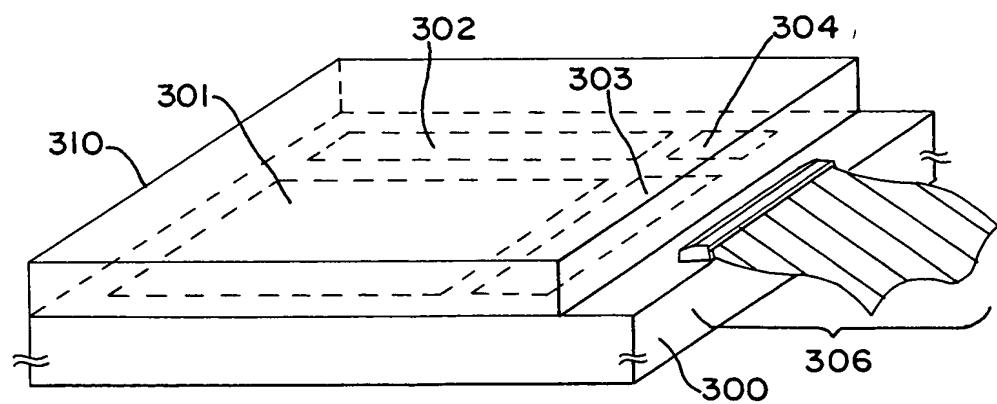




FIG. 12 (A)

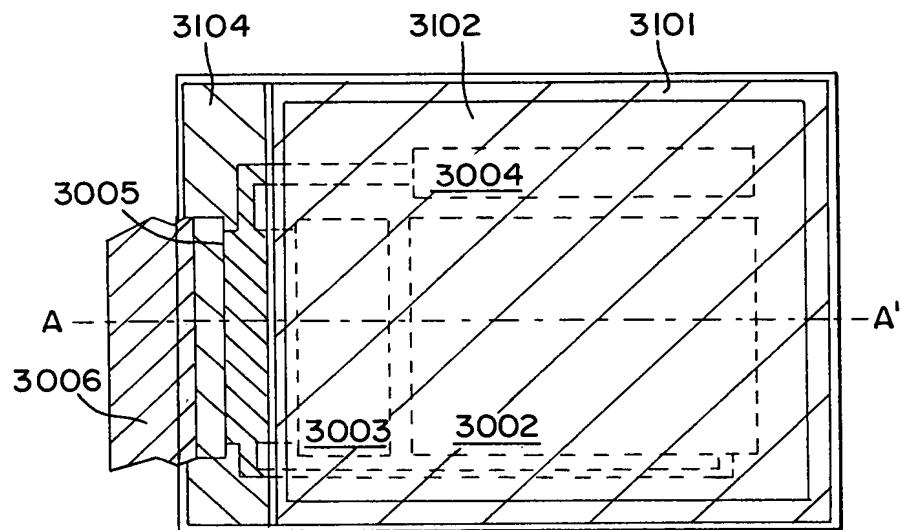


FIG. 12 (B)

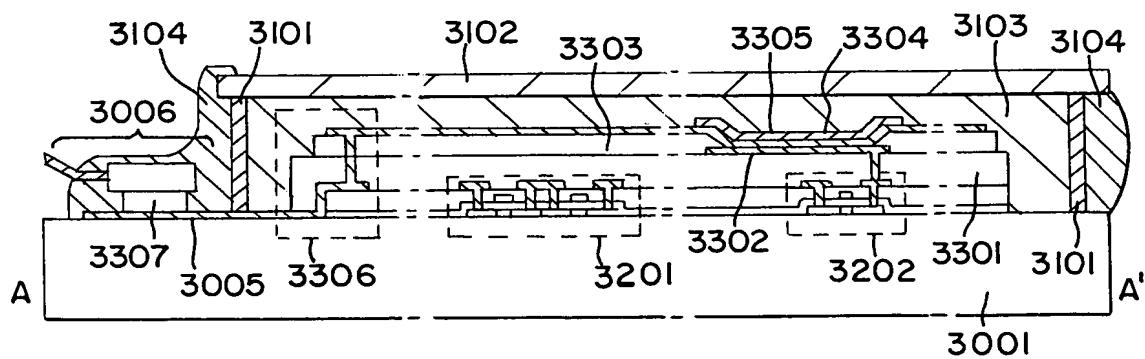




FIG. 13(A)

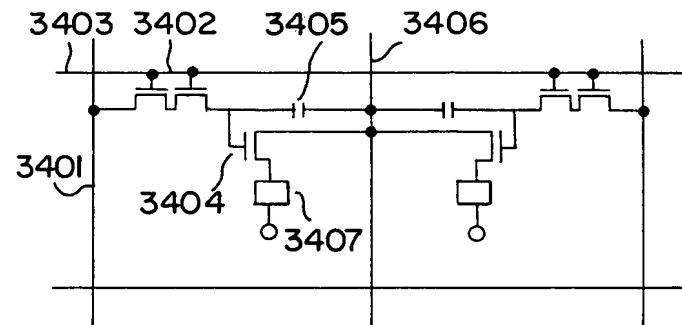


FIG. 13(B)

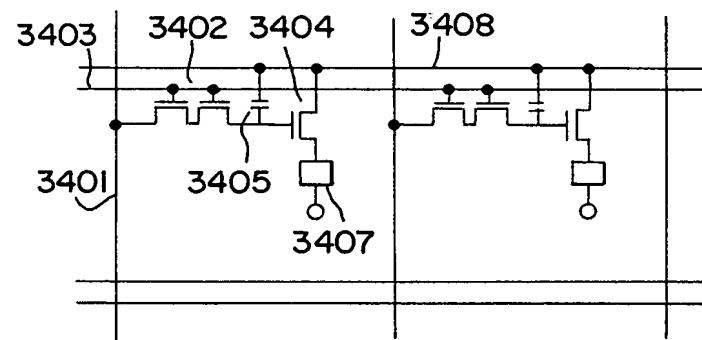


FIG. 13(C)

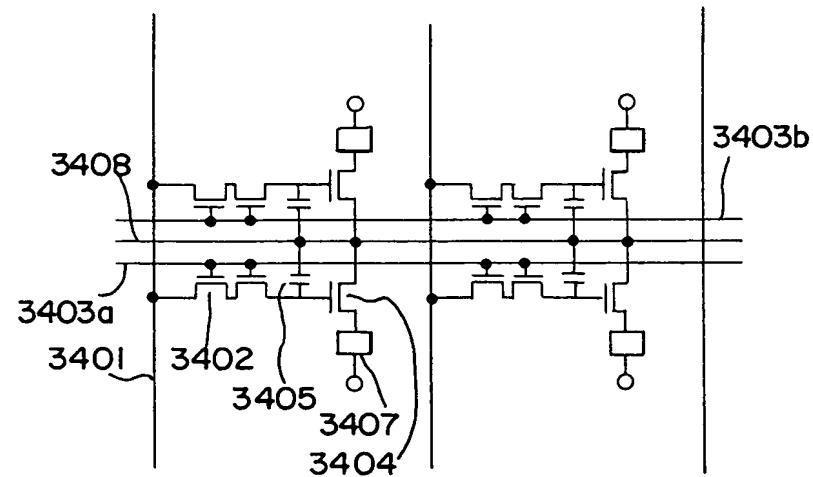




FIG. 14(A)

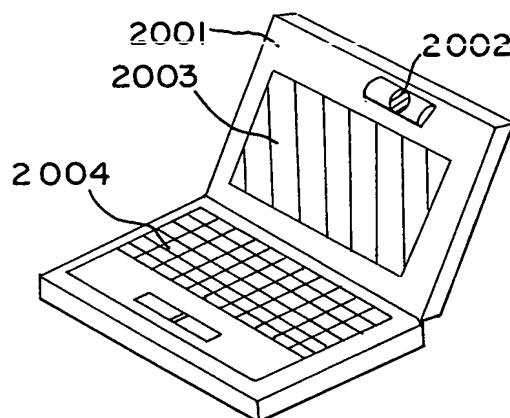


FIG. 14(B)

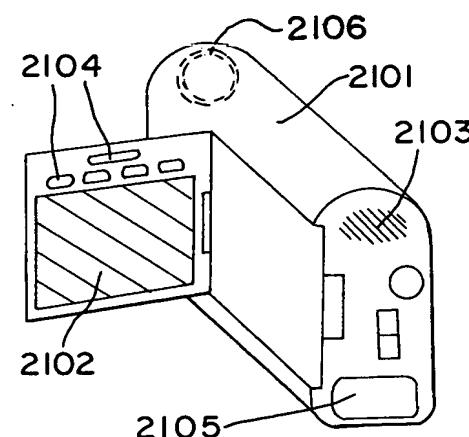


FIG. 14(C)

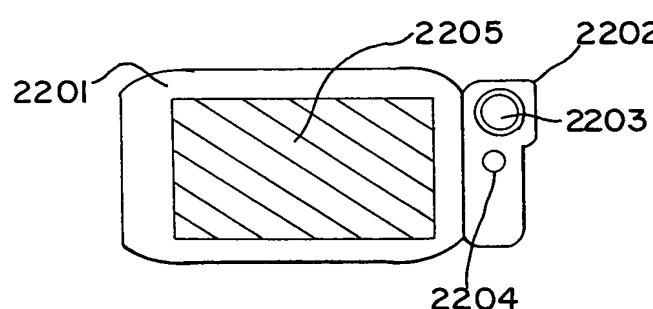


FIG. 14(D)

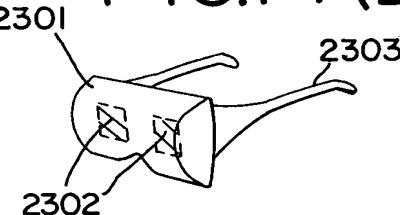


FIG. 14(E)

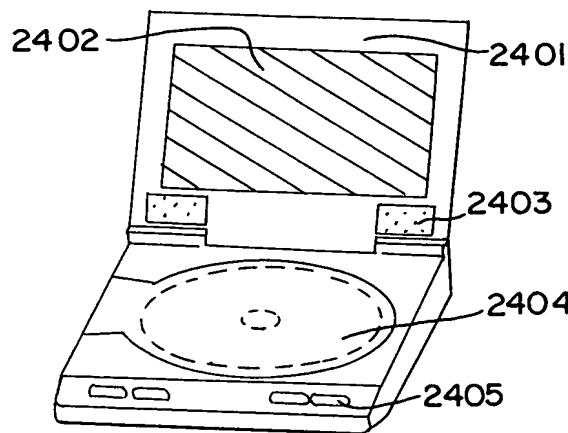


FIG. 14(F)

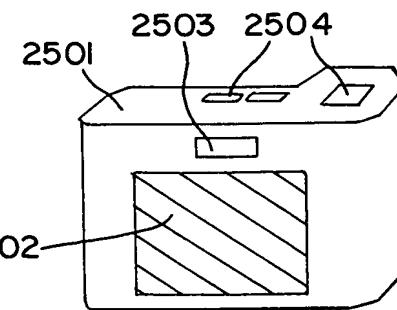




FIG. 15(A)

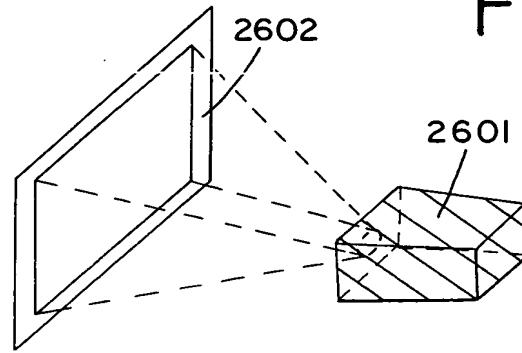


FIG. 15(B)

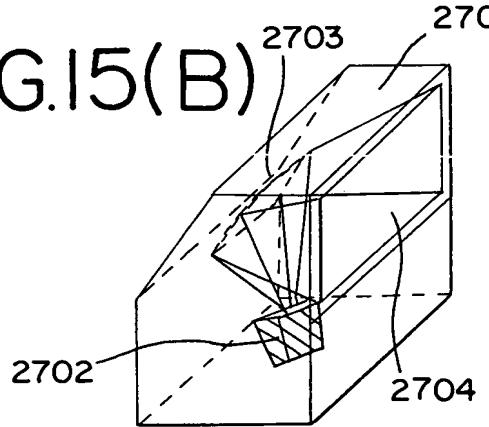


FIG. 15(C) PROJECTION UNIT (THREE-LENS TYPE)

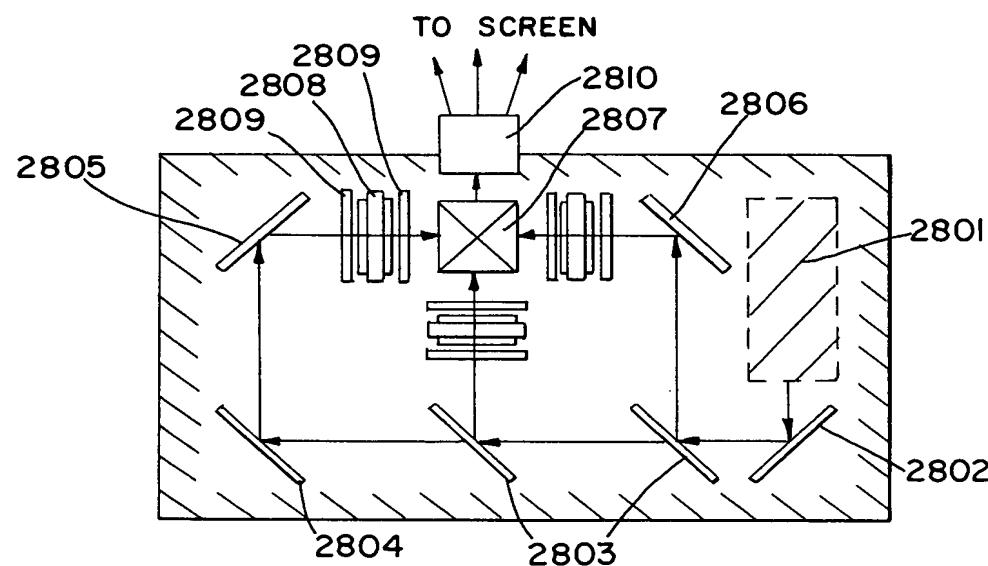


FIG. 15(D)

LIGHT SOURCE
OPTICAL SYSTEM

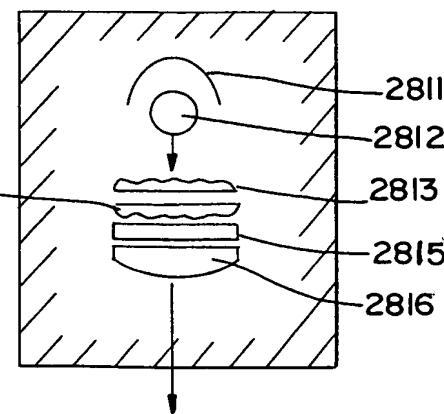




FIG. 16(A)

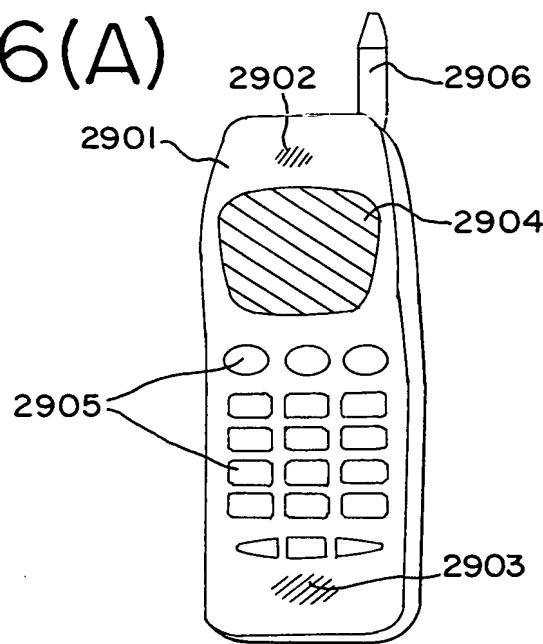


FIG. 16(B)

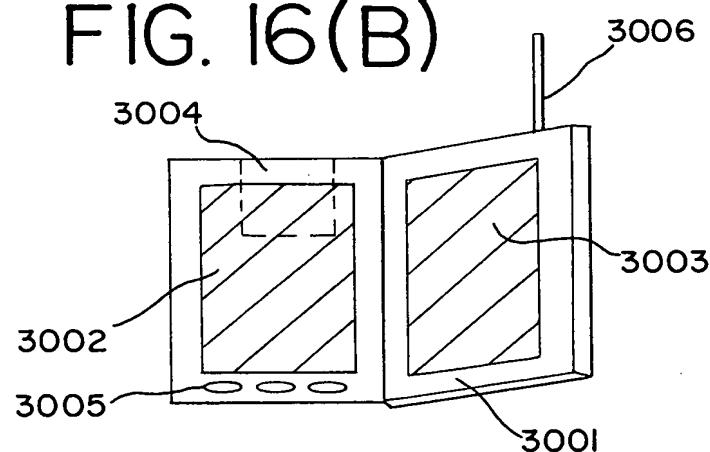


FIG. 16(C)

